

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	338	silicone adj elastomer with (coefficient thermal expansion CTE)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 20:50
L2	17	("20020074086"   "3996187"   "3996189"   "4077943"   "4154714"   "4304895"   "4380367"   "4418165"   "4647282"   "4868251"   "5147396"   "5444106"   "5512609"   "5623029"   "6121368"   "6415093"   "6483981").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/26 20:49
L3	83	silicone adj elastomer with (coefficient thermal expansion CTE) and (chip die ic)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 20:54
L4	2	silicone adj elastomer with (coefficient thermal expansion CTE) with ppm and (chip die ic)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 20:57
L5	2	silicone adj elastomer with (coefficient thermal expansion CTE) with ppm	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 20:57
L6	10	silicone adj elastomer same (coefficient thermal expansion CTE) same ppm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 21:04
L7	17	silicone adj gel same (coefficient thermal expansion CTE) same ppm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 21:15
L8	41	urethane same (coefficient thermal expansion CTE) same ppm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 21:18
L10	9098	(CTE thermal expansion) same (silicone adj elastomer silicone adj gel urethane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 21:52

L11	65	(CTE thermal expansion) same (silicone adj elastomer silicone adj gel urethane) same ppm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 22:05
L12	388	(chip die ic) and (die adj attach compliant adhesive material) adj (layer film adhesive) with (CTE thermal adj expansion) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 22:08
L13	795	(chip die ic) and (thermoset\$4 thermoplastic (die adj attach compliant adhesive material) adj (layer film adhesive)) with (CTE thermal adj expansion) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 22:13
L14	104	(chip die ic) and (thermoset\$4 thermoplastic (die adj attach compliant adhesive material) adj (layer film adhesive)) with (CTE thermal adj expansion) same ppm and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 22:13